What is claimed is:

1. Magnetic ferrite powder,

wherein a peak intensity ratio of Z phase ($M_3Me_2Fe_{24}O_{41}$: M = one or more kinds of alkaline-earth metal, Me = one or more kinds selected from Co, Ni, Mn, Zn, Mg and Cu) of hexagonal ferrite is 30% or higher in X-ray diffraction, and

a peak value of grain size distribution is within a range from 0.1 μm to 3 μm.

2. The magnetic ferrite powder according to claim 1,

wherein one or more kinds selected from borosilicate glass, zinc borosilicate glass, Bi_2O_3 based glass, CuO and Bi_2O_3 are added by 0.5 wt% to 20 wt%.

3. The magnetic ferrite powder according to claim 1,

wherein CuO and Bi_2O_3 are added by 0.5 wt% to 20 wt% in total.

4. The magnetic ferrite powder according to claim 1,

wherein Bi_2O_3 based glass and CuO are added by 3 wt% to 15 wt% in total.

5. The magnetic ferrite powder according to claim 1,

wherein Bi_2O_3 based glass is added by 3 wt% to 7 wt%, and CuO is added by 3 wt% to 7 wt%.

6. Magnetic ferrite powder,

wherein Z phase (where M = Ba, Me = one or more kinds selected from Co, Ni, Mn, Zn, Mg and Cu) indicated as $M_3Me_2Fe_{24}O_{41}$ forms a main phase, and

a powder specific surface area is from 5 m^2/g to 30 m^2/g.

7. The magnetic ferrite powder according to claim 6,

wherein a portion of Ba is substituted with Sr.

8. A sintered body of magnetic ferrite,

wherein a Z phase (M = Ba, Me = one or more kinds selected from Co, Ni, Mn, Zn, Mg and Cu) indicated as $M_3Me_2Fe_{24}O_{41}$ forms a main phase,

CuO and Bi_2O_3 are included by 0.5 wt% to 20 wt% in total,

CuO mainly exists within grains, and

Bi_2O_3 mainly exists at grain boundaries.

9. The sintered body of magnetic ferrite according to claim 8,

wherein a portion of Ba is substituted with Sr.

10. Sintered body of magnetic ferrite,

wherein Z phase (where M = Ba, Me = one or more kinds selected from Co, Ni, Mn, Zn, Mg and Cu) indicated as $M_3Me_2Fe_{24}O_{41}$ forms a main phase, and

Bi_2O_3 based glass and CuO are added by 1 wt% to 20 wt% in total.

11. A multilayer ferrite chip component in which a magnetic ferrite layer and an internal electrode are stacked alternately, the multilayer ferrite chip component comprising an external electrode electrically connected with said internal electrode,

wherein said magnetic ferrite layer has Z phase ($M_3Me_2Fe_{24}O_{41}$: M = one or more kinds of alkaline-earth metal, Me = one or more kinds selected from Co, Ni, Mn, Zn, Mg and Cu) of hexagonal ferrite as a main phase in X-ray diffraction, the magnetic ferrite layer being constituted of sintered body of magnetic ferrite having a mean grain size of 1 to 5 μm, and

said internal electrode is constituted of any one of Ag and an Ag alloy.

12. The multilayer ferrite chip component according to claim 11,

wherein said multilayer ferrite chip component is formed by co-firing said magnetic ferrite layer and said internal electrode layer, and

density of said magnetic ferrite layer is 5 g/cm^3 or higher.

13. The multilayer ferrite chip component according to claim 11,

wherein said magnetic ferrite layer includes CuO and Bi_2O_3 by 0.5 wt% to 20 wt% in total,

CuO mainly exists within grains, and

Bi_2O_3 mainly exists at grain boundaries.

14. The multilayer ferrite chip component according to claim 11,

wherein said magnetic ferrite layer includes Bi_2O_3 based glass and CuO by 1 wt% to 20 wt% in total.

15. A manufacturing method of a multilayer ferrite chip component in which a magnetic ferrite layer and an internal electrode are stacked, comprising the steps of:

mixing raw material powder of magnetic ferrite;

calcining the mixed raw material powder in a temperature range of 1200°C or higher;

milling the obtained calcined body so as to make a peak value of grain size distribution fall into a range from 0.1 to 3 μm;

obtaining a sheet or paste for forming a magnetic layer by using the

obtained milled powder;

obtaining a laminated green body by alternately stacking material for the internal electrode and any one of said sheet and said paste; and

sintering said laminated green body at a temperature lower than 960°C,

wherein said magnetic ferrite layer consists of sintered body of magnetic ferrite having a peak intensity ratio of Z phase ($M_3Me_2Fe_{24}O_{41}$: M = one or more kinds of alkaline-earth metal, Me = one or more kinds selected from Co, Ni, Mn, Zn, Mg and Cu) of hexagonal ferrite at 30% or greater in X-ray diffraction.

16. The manufacturing method of the multilayer ferrite chip component according to claim 15,

wherein a powder specific surface area of each of said raw material powder is 4.5 m^2/g or more.

17. The manufacturing method of the multilayer ferrite chip component according to claim 15,

wherein a powder specific surface area of said milled powder is in a range from 8 m^2/g to 20 m^2/g.